



Product Change Notification

Change Notification #: 114207 - 02

Change Title: Intel® Ethernet Converged Network Adapter X520-SR2 (Spring Fountain), MM #s: 900137, 901223, 927247,

PCN 114207-02, Product Design, Label, Product Marking, Product Material,

Updates to Bracket Design, Optic transceiver, Regulatory Mark and Labels,

Reason for Revision: Modify text in label combination to include FCC.

Date of Publication: April 27, 2016

Key Characteristics of the Change:

Product Design, Label, Product Marking, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 20, 2016
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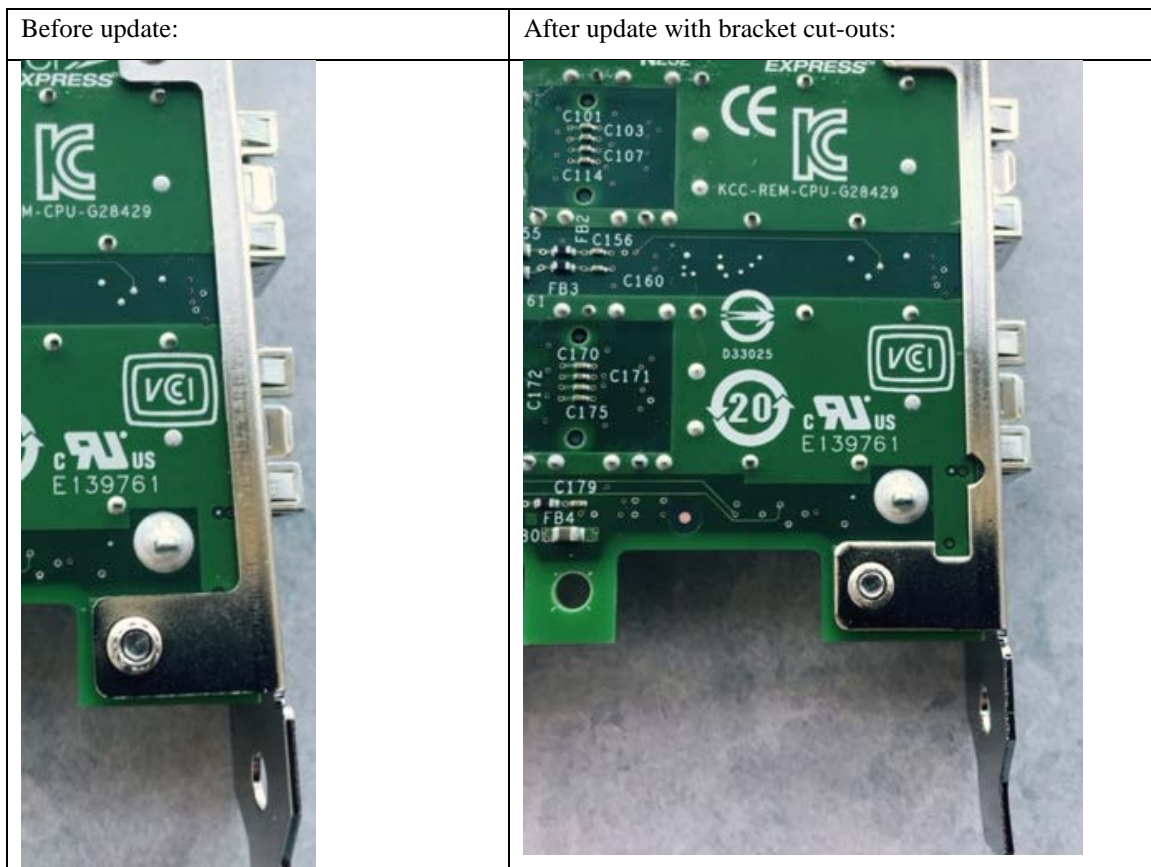
Description of Change to the Customer:

Reason for Revision: Modify text in label combination to include FCC.

Reason for Revision 01: Adding Avago Optic part numbers and changing the Ready to Receive date.

The Intel® Ethernet Converged Network Adapter X520-SR2, product codes E10G42BFSR, E10G42BFSRBLK, E10G42BFSRG1P5 will undergo the following changes:

1. To improve the bracket clearance with via pads, the bracket has been re-designed with 2 notches. The part number on the Standard height bracket will change from E33052-003 to E33052-004. The part number on the Low Profile bracket will change from E33054-002 to E33054-003.



- In order to keep pace with the rapidly growing volume and competitive demand, our Optical Transceiver suppliers have made enhancements to their SFP+ SR and LR optical transceiver solutions through what are considered minor changes.

Description of Key Changes:

10Gb SFP+ SR

- A next generation TIA will be introduced to improve stressed receiver sensitivity performance.
- Module component list has been modified with supplier designed ICs (laser driver, EEPROM, limiting amplifier) and TIA
- Pin housing changed from a fixed to a moving solution
- Visual alignment of supplier bail solutions

10Gb SFP+ LR

- Introduction of Next Generation SFP+ LR Transmitter Optical Sub-Assembly (TOSA);
- Module component list has been modified with supplier designed ICs (laser driver, EEPROM, limiting amplifier) and TIA
- In addition, the solution has a change to the pin housing from fixed to a moving solution as well as a change of the bail from plastic to metal

Other

- Alternate sources have been added to supplier approved manufacturer list for photodiode and micro controller for SR and LR solutions.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

- There may be some noticeable visual changes to the module form and fit but customers should not experience issues using it in the existing applications. The customers should expect no differences in functionality, quality and reliability. The device specification and manufacturing process will be same to the current products.

- All changes are deemed low-risk due to minor modification and have been validated and qualified by Intel.
- Items impacted and new part numbers:

Current IPN	New IPN	Current MPN	New MPN	Current MPN	New MPN
		Finisar	Finisar	Avago	Avago
E65689-001	E65689-003	FTLX8571D3BCV-IT	FTLX8571D3BCVIT1	AFBR-703SDZ-IN2	AFBR-709DMZ-IN2
E65689-002	E65689-004	FTLX8571D3BCV-I3	FTLX8571D3BCVI31	N/A	N/A
E65685-001	E65685-003	FTLX1471D3BCV-IT	FTLX1471D3BCVIT1	AFCT-701SDZ-IN2	AFCT-739DMZ-IN2
E65685-002	E65685-004	FTLX1471D3BCV-I3	FTLX1471D3BCVI31	N/A	N/A

Old Optic E65685-001



New Optic E65685-003



Old Optic E65689-001



New Optic E65689-003



3. Australia Regulatory Mark Change

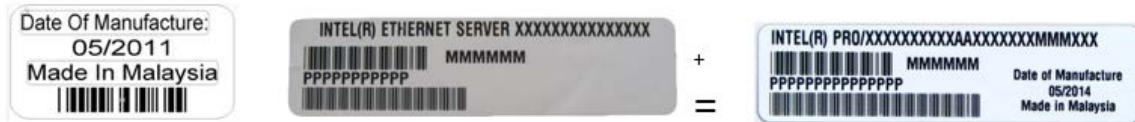
- The Australian Communications and Media Authority's (ACMA) labeling arrangements to reflect regulatory compliance changed on 1 March 2013, to be phased in over a three-year transition period. Products shipping March 1, 2016 need to be labeled with the "RCM" mark.
 - Per ACMA requirements, Intel will be changing the C-Tick regulatory mark on all products to the "RCM" mark.
 - Mark will be updated in two ways, depending on how the current C-Tick mark is already on products:
 - If C-Tick mark is currently on PCB silkscreen, Intel will apply a label with RCM mark to cover current mark.
 - If C-Tick mark is currently printed on a label, Intel will replace the mark so labels will be printed with new mark.
- See for picture of "C-Tick" versus "RCM" mark




4. Where applicable this will affect OEMG and Retail NICs.

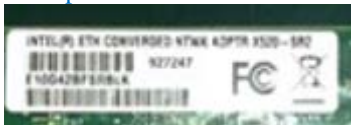
Combining of KCC, **and/or the FCC**, and/or Date of Manufacture label with the product ID label to minimize labels on the board. In addition we'll be taking the opportunity to:

Remove	Reg label	KCC_DOM or FCC
Edit	PID label	Product ID
To Include	PID label	Product ID + DOM or Product ID + DOM + other



The WEEE label  maybe incorporated into the Intel branded PID.

Example of PID Label with FCC and WEEE.



Customer Impact of Change and Recommended Action:

Customers can expect to receive mixed inventory until current inventory levels are depleted.
Intel anticipates no functional impact to customer but encourages customer to understand the changes.
Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
E10G42BFSR	900137	E68788-007	E68785-007	E68788-008	E68785-008
E10G42BFSRG1P5	901223	E58747-007	E70854-008	E58747-008	E70854-009
E10G42BFSRBLK	927247	G90056-001	E68785-007	G90056-002	E68785-008

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 30, 2015	00	Originally Published PCN
December 15, 2015	01	Adding Avago Optic part numbers and changing the Ready to Receive date
April 27, 2016	02	Modify text in label combination to include FCC.



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